



Material Content Data Sheet



Sales Product Name		IPG20N10S4L-22		Issued		24. January 2018		
MA#		MA001607832						
Package		PG-TDSON-8-4		Weight*		97.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.263	3.34	3.34	33442	33442
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		137	
	non noble metal	iron	7439-89-6	0.045	0.05		458	
	non noble metal	copper	7440-50-8	44.654	45.77	45.83	457609	458204
	non noble metal	aluminium	7429-90-5	0.713	0.73	0.73	7306	7306
wire	non noble metal	aluminium	7429-90-5	0.713	0.73	0.73	7306	7306
encapsulation	organic material	carbon black	1333-86-4	0.088	0.09		902	
	plastics	epoxy resin	-	6.248	6.40		64025	
	inorganic material	silicondioxide	60676-86-0	37.662	38.60	45.09	385955	450882
leadfinish	non noble metal	tin	7440-31-5	1.308	1.34	1.34	13400	13400
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	492	493
solder	non noble metal	tin	7440-31-5	0.071	0.07		725	
	noble metal	silver	7440-22-4	0.088	0.09		907	
	non noble metal	lead	7439-92-1	3.380	3.46	3.62	34641	36273
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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